

300mm Semi-Automatic BG Tape Laminator

RAD-3500m/12



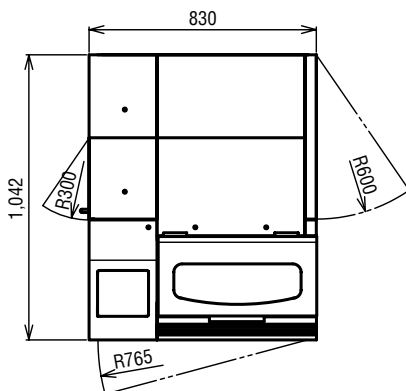
Outline

- Semi-automatic BG Tape laminator.
- Once the operator supplies the wafer, back grinding tape lamination and tape cutting around the wafer periphery are performed.
- As an option, a heater function maybe added to tables and press rollers.

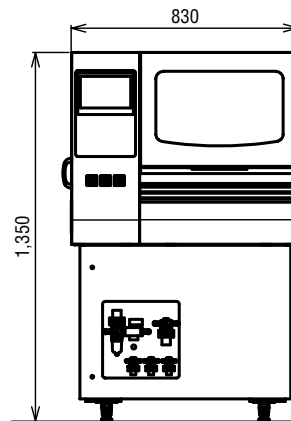
Suitable Tapes · BG Tape : Adwill E series, P series

External View

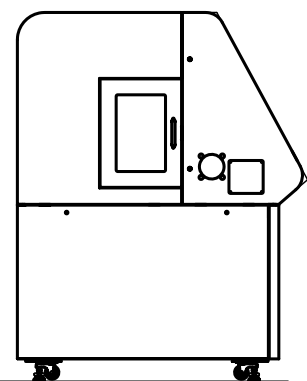
Unit:mm



Top View



Front View



Left Side View

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
Air Supply	Capacity	: 0.7kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >130L/min (ANR)

Applicable Wafer Size 150mm, 200mm, 300mm

Size
Width : 830mm
Depth : 1,042mm
Height : 1,350mm

Weight 250kg

Processing Capacity 40sec/wafer (excludes setting time)



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